

ABSTRACT

The present invention relates to a release coating composition that may be applied to a film that may then be used as a substrate useful for applications requiring release for a broad range of temperatures and high humidity conditions, which temperatures may range from about 20°C to about 210°C. These applications include release substrate used in the manufacture of calendared cured sheet rubber and molding paste composites, such as sheet molding compound (SMC), thick molding compound (TMC), bulk molding compound (BMC) and fiberglass composites. The release coating composition comprises a solution of a hydroxypropyl methylcellulose having hydroxypropyl molar substitution of from 0 to about 0.82. In a preferred form, particulate solids are present in the composition.